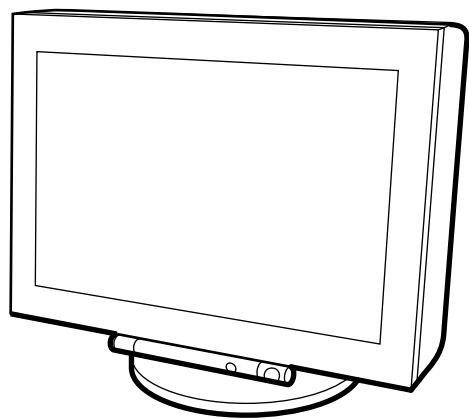


GDM-FW9012

SERVICE MANUAL

N.Hemisphere Model

Chassis No. SCC-L34E-A



G1W

 CHASSIS

SPECIFICATIONS

CRT	0.23 – 0.27 mm aperture grille pitch 24 inches measured diagonally 90-degree deflection FD Trinitron	Deflection frequency*	Horizontal: 30 to 121 kHz Vertical: 48 to 160 Hz
Viewable image size	Approx. 482.1 × 308.2 mm (w/h) (19 × 12 1/4 inches) 22.5" viewing image	AC input voltage/current Power consumption	100 to 240 V, 50/60 Hz, 2.2 – 1.2 A Approx. 160 W (with no USB devices connected)
Resolution	Maximum (16:10) Horizontal: 2304 dots Vertical: 1440 lines Maximum (4:3) Horizontal: 2048 dots Vertical: 1536 lines Recommended (16:10) Horizontal: 1920 dots Vertical: 1200 lines	Operating temperature Dimensions	10°C to 40°C Approx. 571.5 × 500 × 522.5mm(w/h/d) (22 1/2 × 19 3/4 × 20 5/8 inches)
Input signal levels	Video signal Analog RGB: 0.700 Vp-p (positive), 75 Ω SYNC signal H/V separate or composite sync: TTL 2 kΩ, Polarity free Sync on Green: 0.3 Vp-p (negative)	Mass Plug and Play Supplied accessories	Approx. 42 kg (92 lb 10 oz) DDC1/DDC2B/DDC2Bi, GTF** • Power cord (1) • Video signal cable (1) • USB cable (1) • Exclusive Power Mac G3/G4 adapter (1) • Warranty card (1) • Notes on cleaning the screen's surface (1) • This instruction manual (1)
Standard image area	16:10 Approx. 474 × 296 mm (w/h) (18 3/4 × 11 3/4 inches) 4:3 Approx. 395 × 296 mm (w/h) (15 5/8 × 11 3/4 inches) 5:4 Approx. 370 × 296 mm (w/h) (14 5/8 × 11 3/4 inches)	* Recommended horizontal and vertical timing condition • Horizontal sync width duty should be more than 4.8% of total horizontal time or 0.8 μs, whichever is larger. • Horizontal blanking width should be more than 2.3 μsec. • Vertical blanking width should be more than 450 μsec. ** If the input signal is Generalized Timing Formula (GTF) compliant, the GTF feature of the monitor will automatically provide an optimal image for the screen. Design and specifications are subject to change without notice.	

24-inch Color Monitor

HP

SECTION 3

ADJUSTMENTS

Note: Hand degauss must be used on stand-by or power-off condition.

This model has an automatic earth magnetism correction function by using an earth magnetism sensor and a LCC coil. When using a hand degauss while monitor (LCC coil) is being operated, it sometimes gets magnetized, and the system may not work properly as a result.

• Landing Rough Adjustment

1. Enter the full white signal. (or the full black dots signal).
2. Adjust the contrast to the maximum.
3. Make the screen monogreen.
Note: Off the outputs from R ch and B ch of SG.
4. Reverse the DY, and adjust coarsely the purity magnet so that a green raster positions in the center of screen.
5. Adjust the tilt of DY, and fix lightly with a clamp.

Note: "TILT" = "128".

• Landing Fine Adjustment

1. Put the set inside the Helmholtz coil. ("LCC SW" = "12")
2. Input the single green signal and set the "CONTRAST" = "255".

Note: After the W/B adjustment with 9300K, measure an average of ΣI_k when a full white signal is entered in the CONT MAX/BRT CENT status. Then make adjustment so that the specified screen can be attained after aging for 2 hours with I_k equivalent to 30% of the average value.

3. Demagnetize the metal part of the chassis with the hand degausser and coil degausser, and the CRT surface with the hand degausser.
Input AC 230V to AC IN, turn on and off the power to perform auto degaussing. (Perform auto degaussing by setting "FUNCTION SW" = 1. Return to the original value after use.)
Demagnetize the CRT surface with the hand degausser again.

Note:

- (1) Hand degauss must be used on stand-by or power-off condition.

This model has an automatic earth magnetism correction function by using an earth magnetism sensor and a LCC coil. When using a hand degauss while monitor (LCC coil) is being operated, it sometimes gets magnetized, and the system may not work properly as a result.

- (2) Adjust in a non-magnetic field.
- (3) If adjusting in a magnetic fields, add the shift from the non-magnetic field in your estimation.
4. Attach the wobbling coil to the designated part of the CRT neck.
5. Attach the sensor of the landing adjustment unit on the CRT surface.

6. Adjust the DY position and purity, and the DY tilt, and landing of the center and 4 corners with the landing checker.

After adjustment, set “LCC SW” to “13”.

- Write terrestrial magnetism sensor reading VX and VY to “LCC VX” and LCC VY” respectively. Adjust the landing by moving “LCC NS”, “LCC LT”, “LCC LB”, “LCC RT” and “LCC RB”. However, the register adjustment must be limited within the following range.

“LCC NS” 128 ± 45

“LCC LT”, “LCC LB”, “LCC RT”, “LCC RB” 128 ± 40

Save the service data.

- * Adjustment and measurement should be made at the points one inch inside the fluorescent screen.

7. Tighten DY screw.

Note: Torque 22 ± 2 kg.cm (2.2 ± 0.2 Nm) auto degauss it.

8. For the up/down swing, swing the DY and insert a wedge so that the up and down pins are equal at the top and bottom. Adjust the H.TRP VR of DY so that the horizontal trapezoid is equal at the left and right. Insert the wedge firmly so that the DY does not shake.

9. Check the landing of each corner, and if it does not satisfy the specification, adjust the landing of four corners using “LCC LT”, “LCC LB”, “LCC RT” and “LCC RB”.

However, the register adjustment must be limited within the following range.

“LCC NS” 128 ± 15

<Specifications>

Adjust so that the green is within the specification given right.

4 corner adjust target : within ± 1

(μ m)

0 ± 3	0 ± 7.5	0 ± 3
0 ± 3	0 ± 7.5	0 ± 3
0 ± 3	0 ± 7.5	0 ± 3

(μ m)

± 6	± 6	± 6
± 6	± 6	± 6
± 6	± 6	± 6

The red and blue must be within the specification given right with respect to the green.

(μ m)

10	10	10
10	7	10
10	10	10

A difference between red and blue must be within the specification given right.

“LCC LT”, “LCC LB”, “LCC RT”, “LCC RB”

128 ± 45

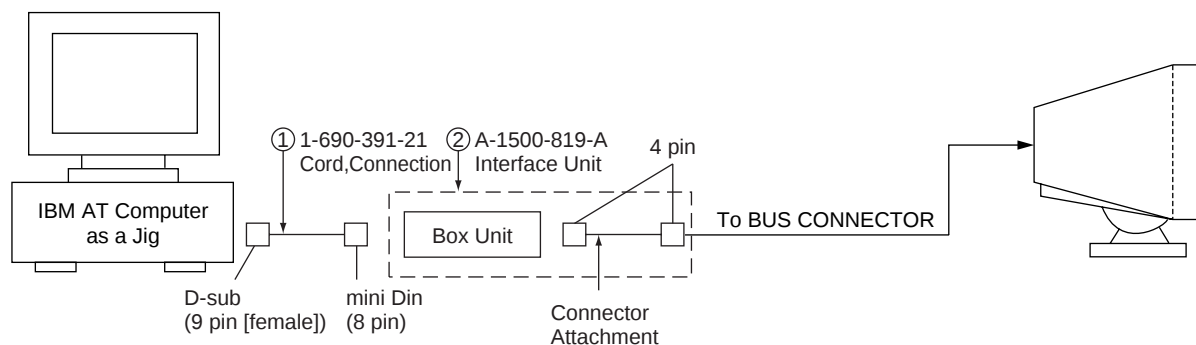
After adjustment, save the service data.

10. Remove the sensor and wobbling coil.

11. Switch the signal to R.G.B., and check that each color is pure.

12. Check that the DY is not tilting, and fix the purity Mg with a white pen. Fix wedges with RTV.

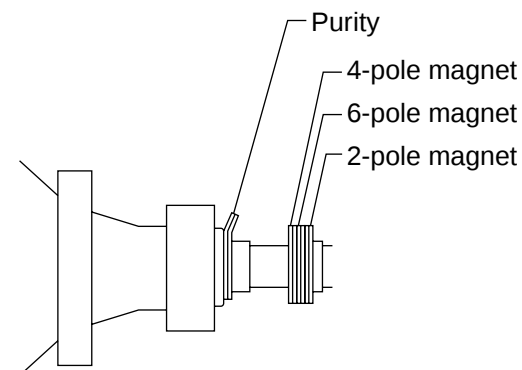
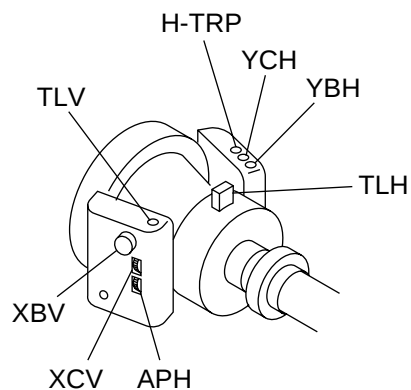
Connect the communication cable of the computer to the connector located on the D board. Run the service software and then follow the instruction.



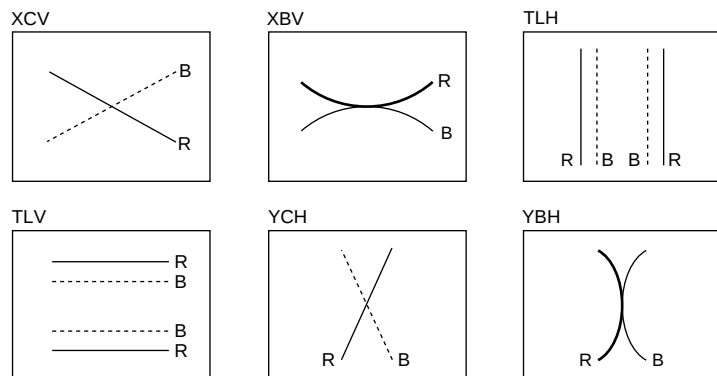
*The parts above (① and ②) are necessary for DAS adjustment.

• Convergence Rough Adjustment

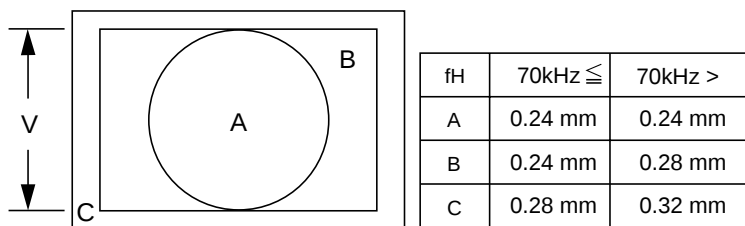
- (1) Receive an image of the white crosshatch signals (white lines on black).
- (2) Place the protrusions of the 6-fold poles magnet attached to the CRT neck upon each other.
- (3) Make rough adjustment of the H and V direction convergence by using 4-fold poles magnet.



* Set so that the protruding parts of the 2 magnet rings agree with each other.



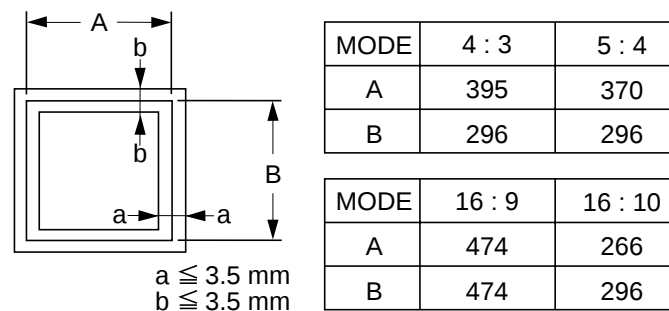
• Convergence Specification



• White Balance Adjustment Specification

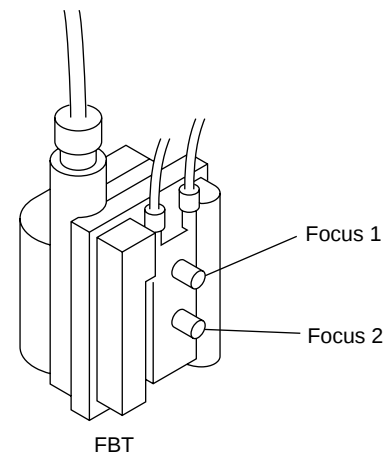
- 9300K
 $x = 0.283 \pm 0.015$
 $y = 0.298 \pm 0.015$
 (All White)
- 6500K
 $x = 0.313 \pm 0.015$
 $y = 0.329 \pm 0.015$
 (All White)
- 5000K
 $x = 0.346 \pm 0.015$
 $y = 0.359 \pm 0.015$
 (All White)

• Vertical and Horizontal Position and Size Specification

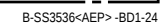


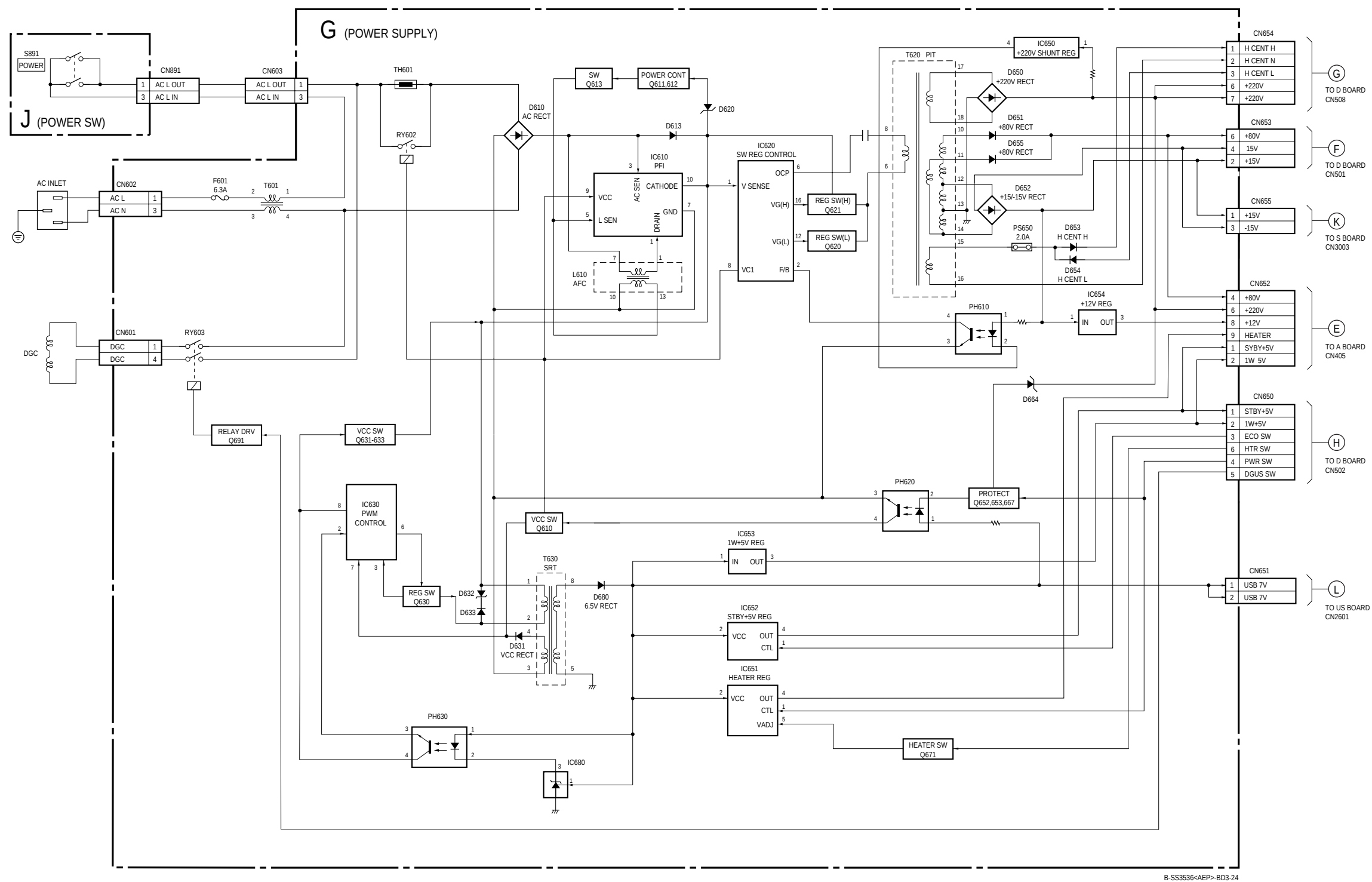
• Focus adjustment

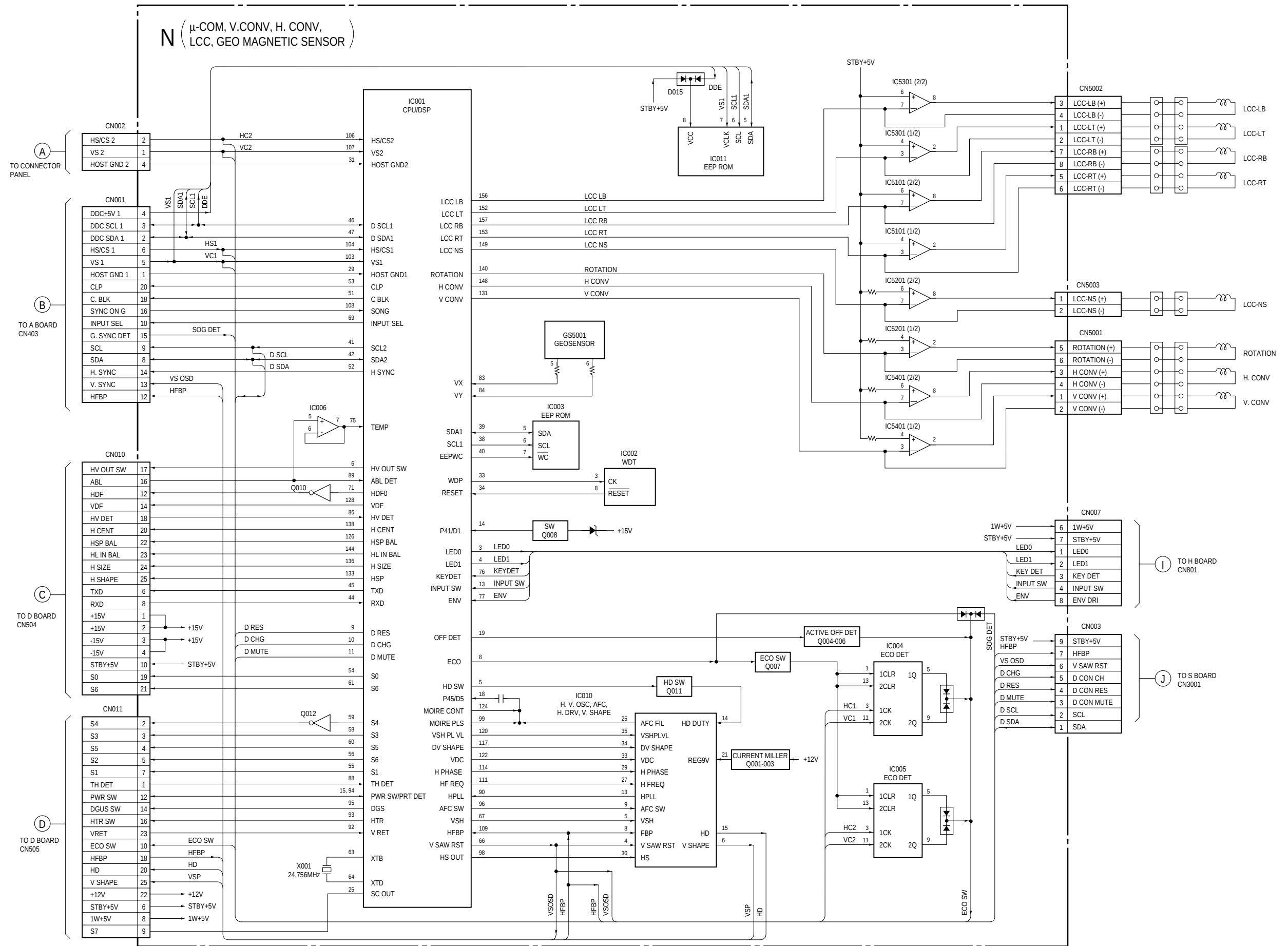
Adjust the focus volume 1 and 2 for the optimum focus.



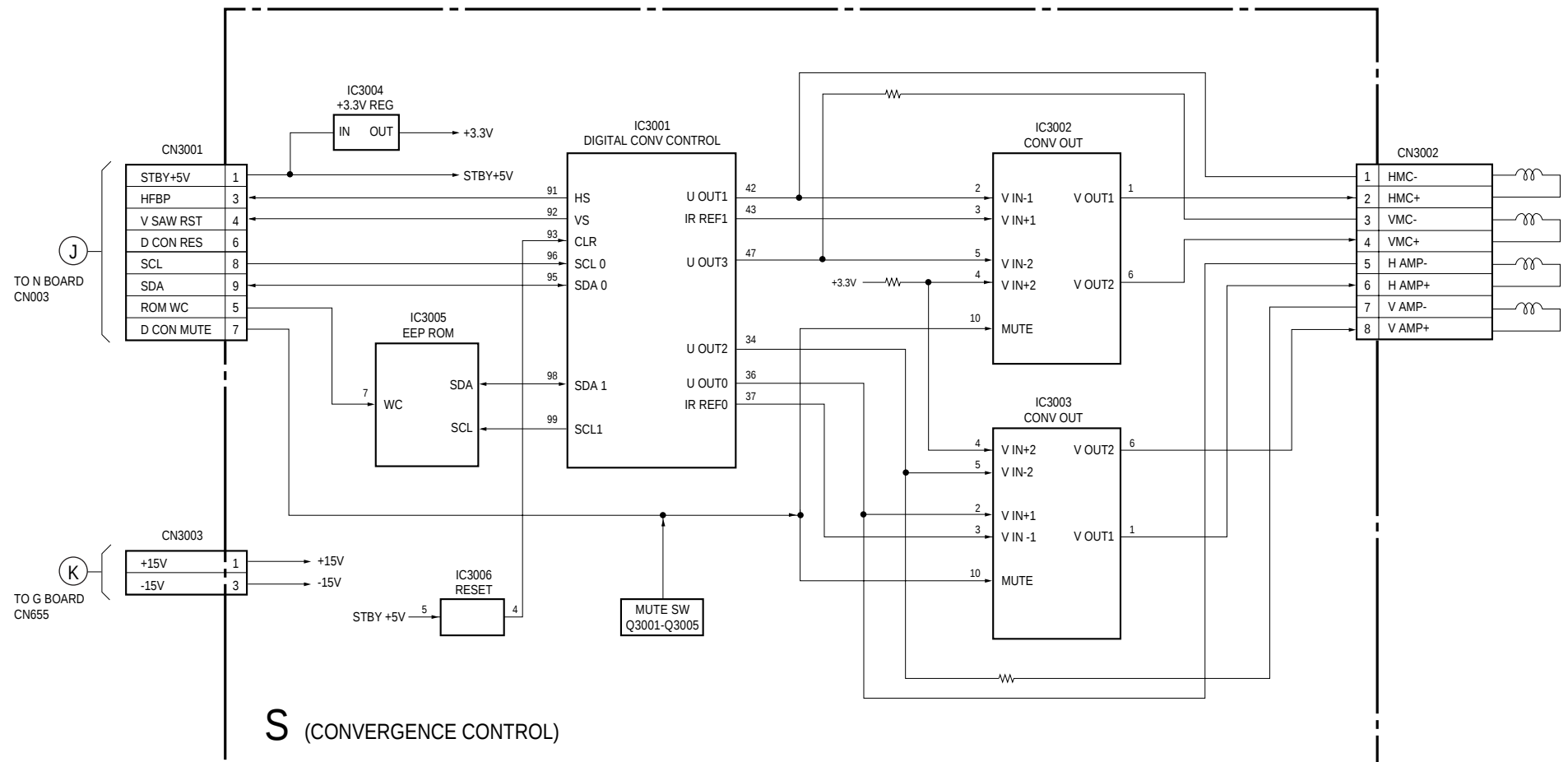
4-1. BLOCK DIAGRAMS



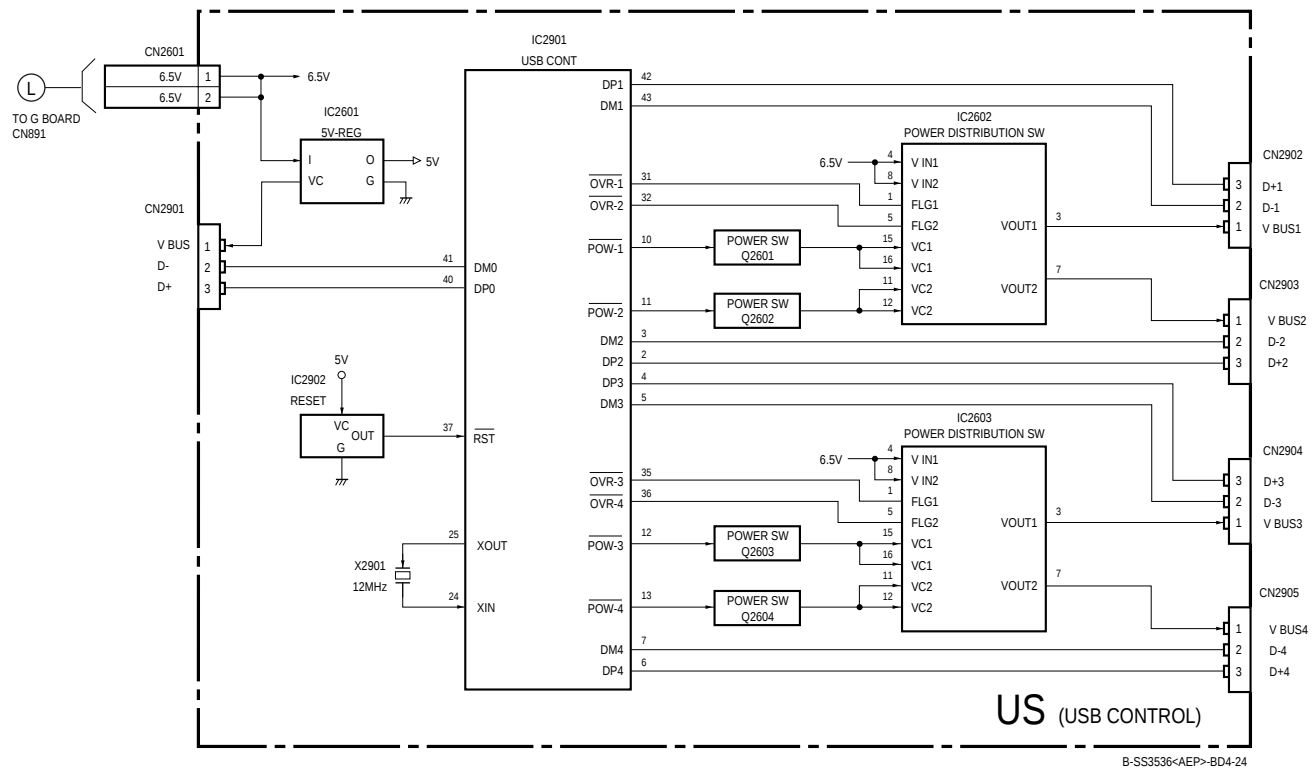
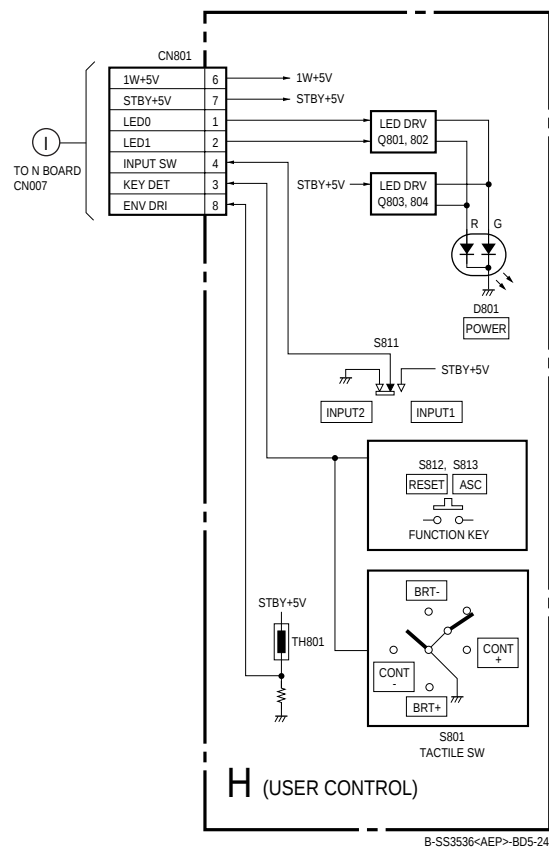




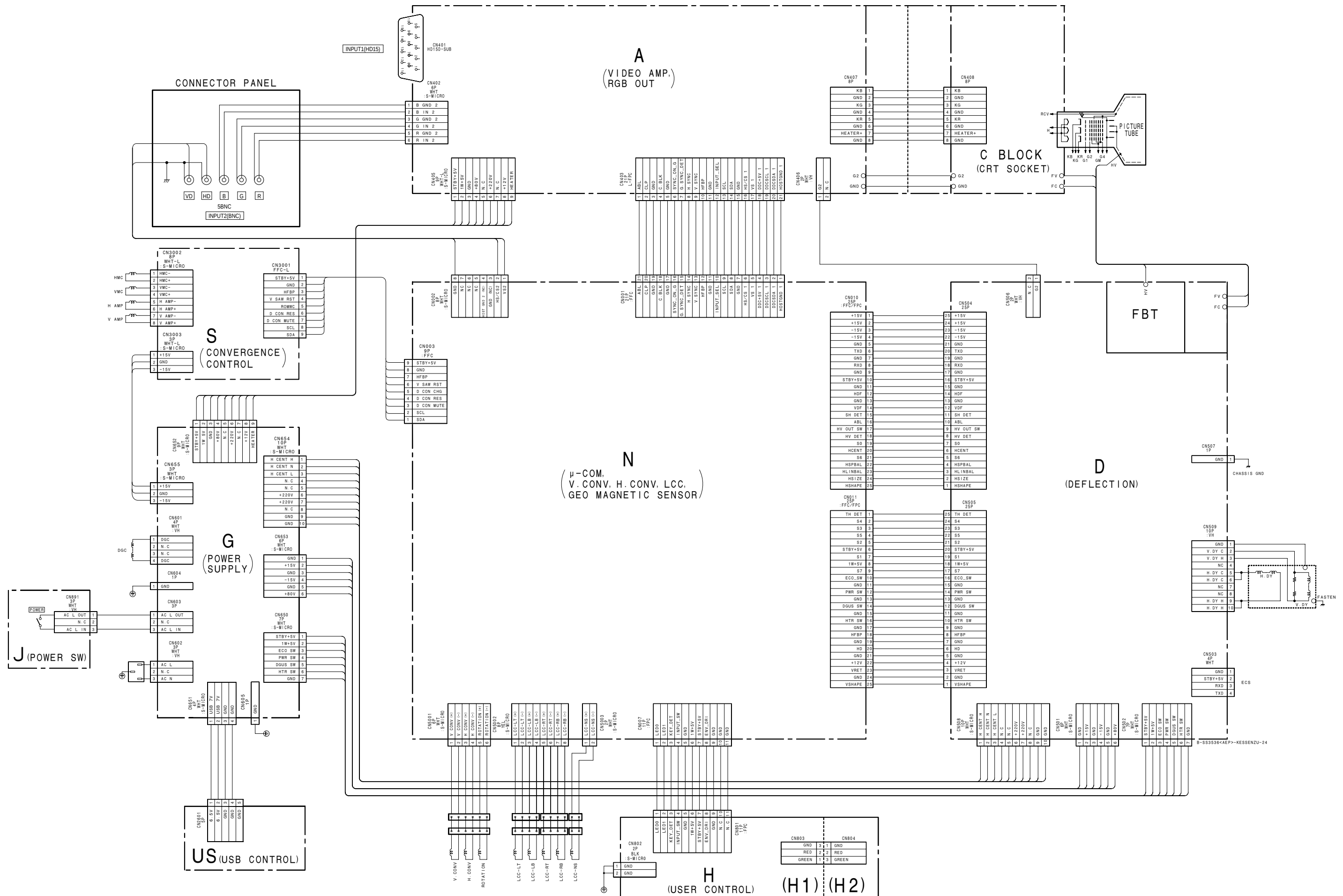
B-S53536<AEP>-BD2-24



B-SS3536<AEP>-BD6-24



4-2. FRAME SCHEMATIC DIAGRAM



4-4. SCHEMATIC DIAGRAMS AND PRINTED WIRING BOARDS

Note:

- All capacitors are in μF unless otherwise noted. (pF: $\mu\mu\text{F}$)
Capacitors without voltage indication are all 50 V.
- Indication of resistance, which does not have one for rating electrical power, is as follows.

Pitch: 5 mm

Rating electrical power 1/4 W (CHIP : 1/10 W)

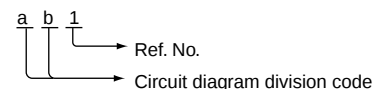
- All resistors are in ohms.
-  : nonflammable resistor.
-  : fusible resistor.
-  : internal component.
-  : panel designation, and adjustment for repair.
- All variable and adjustable resistors have characteristic curve B, unless otherwise noted.
-  : earth-ground.
-  : earth-chassis.
- The components identified by  in this basic schematic diagram have been carefully factory-selected for each set in order to satisfy regulations regarding X-ray radiation.
Should replacement be required, replace only with the value originally used.
- When replacing components identified by  , make the necessary adjustments indicated. (See page 2-1)
- When replacing the part in below table, be sure to perform the related adjustment.
- All voltages are in V.
- Readings are taken with a 10 M Ω digital multimeter.
- Readings are taken with a color-bar signal input.
- Voltage variations may be noted due to normal production tolerances.
- * : Can not be measured.
- Circled numbers are waveform references.
-  : B + bus.
-  : B – bus.

Note: The components identified by shading and mark  are critical for safety. Replace only with part number specified.

Note: Les composants identifiés par un tramé et une marque  sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

- Divided circuit diagram

One sheet of D board circuit diagram is divided into three sheets, each having the code D- to D-. For example, the destination  on the code D- sheet is connected to  on the D- sheet.



	Part Replaced (◀▶)	
HV ADJ	RV901	
	Part Replaced (◻)	
HV Regulator Circuit Check	D Board	C901, R923, R924, R929, R943, T902(FBT) • Mounted D Board
HV Protector Circuit Check	D Board	C922, C926, D912, D915, D921, Q907, Q908, R921, R922, R932, R937, R939, T902(FBT) • Mounted D Board
Beam Current Protector Circuit Check	D Board	C921, C933, D901, D913, R920, R928, R930, 931, T902(FBT) • Mounted D Board
	N Board	IC001, R031, R032 • Mounted N Board

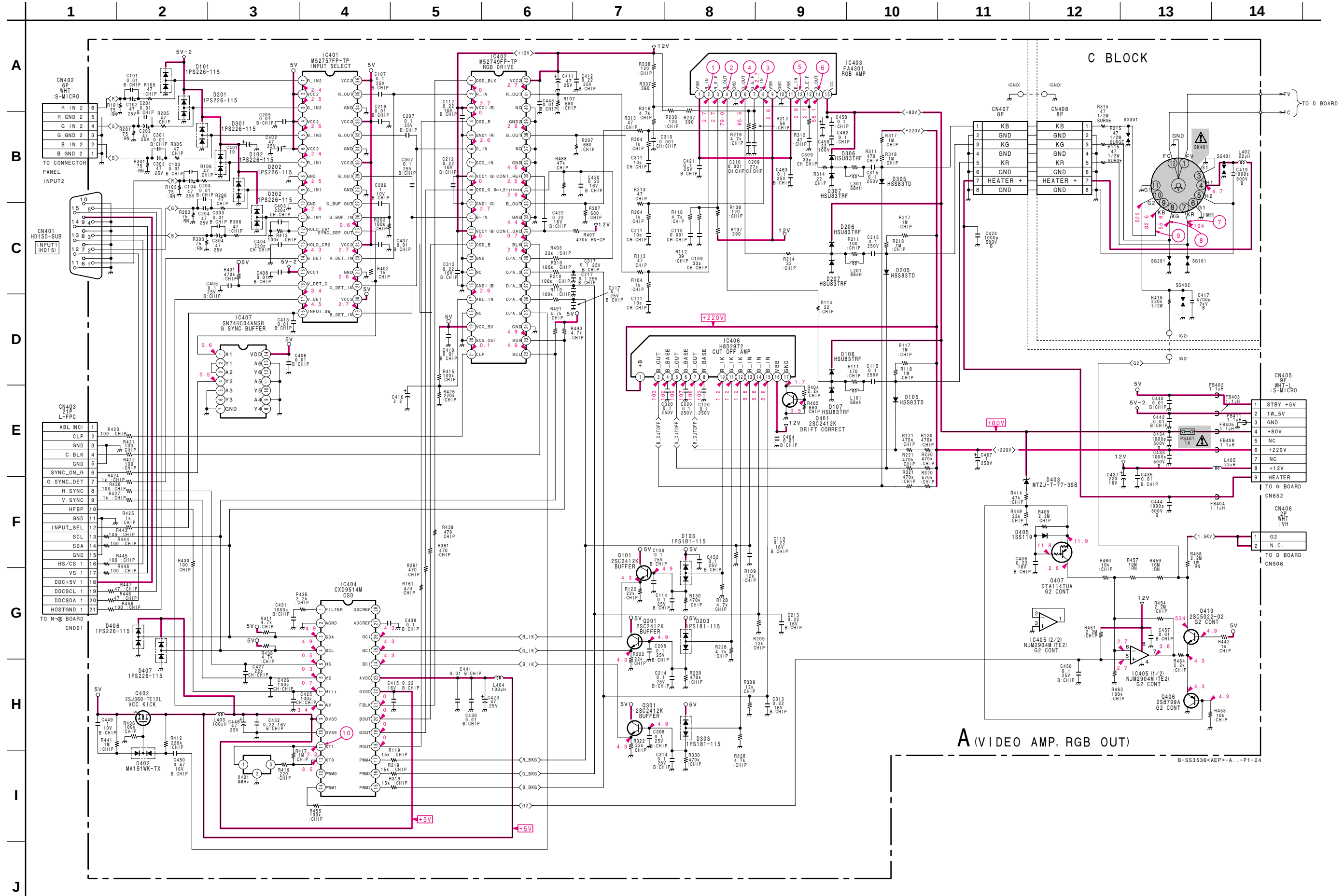
Terminal name of semiconductors in silk screen printed circuit (✱)

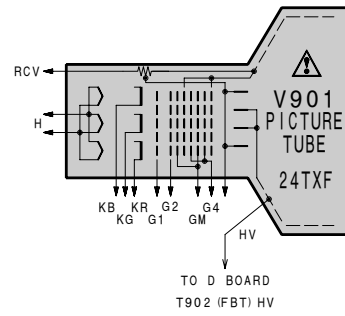
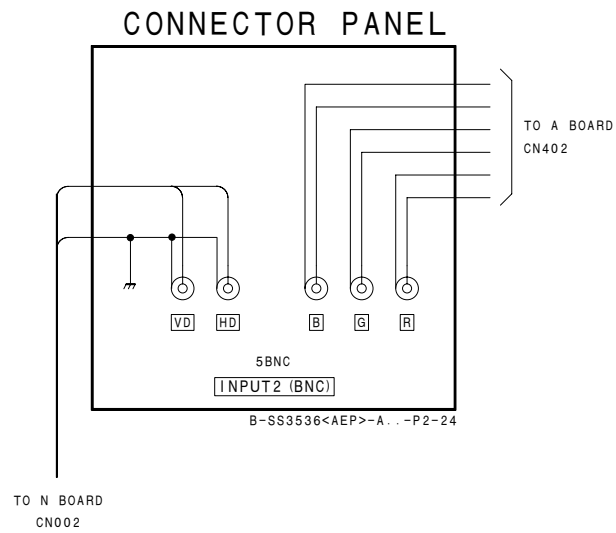
	Device	Printed symbol	Terminal name	Circuit
①	Transistor		Collector Base Emitter	
②	Transistor		Collector Base Emitter	
③	Diode		Cathode Anode	
④	Diode		Cathode Anode (NC)	
⑤	Diode		Cathode Anode (NC)	
⑥	Diode		Common Anode Cathode	
⑦	Diode		Common Anode Cathode	
⑧	Diode		Common Anode Anode	
⑨	Diode		Common Anode Anode	
⑩	Diode		Common Cathode Cathode	
⑪	Diode		Common Cathode Cathode	
⑫	Diode		Anode Anode Cathode	
⑬	Transistor (FET)		Drain Source Gate	
⑭	Transistor (FET)		Drain Source Gate	
⑮	Transistor (FET)		Source Drain Gate	
⑯	Transistor		Emitter Collector Base	
—	Discrete semiconductot			

(Chip semiconductors that are not actually used are included.)

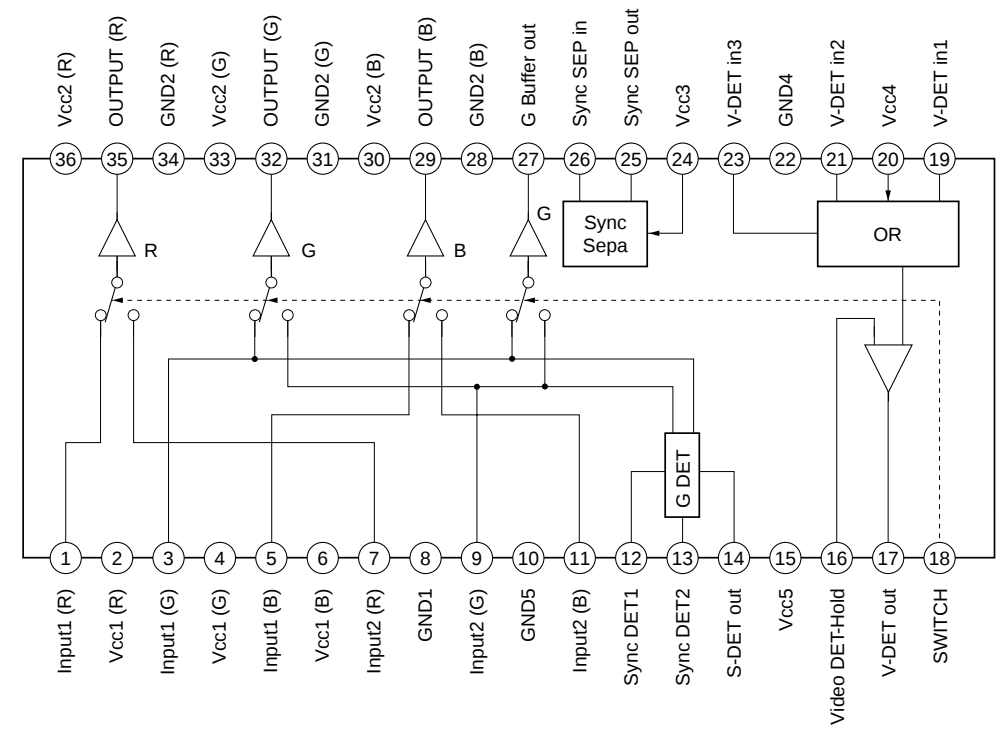
Ver.1.6

(1) Schematic Diagram of A Board

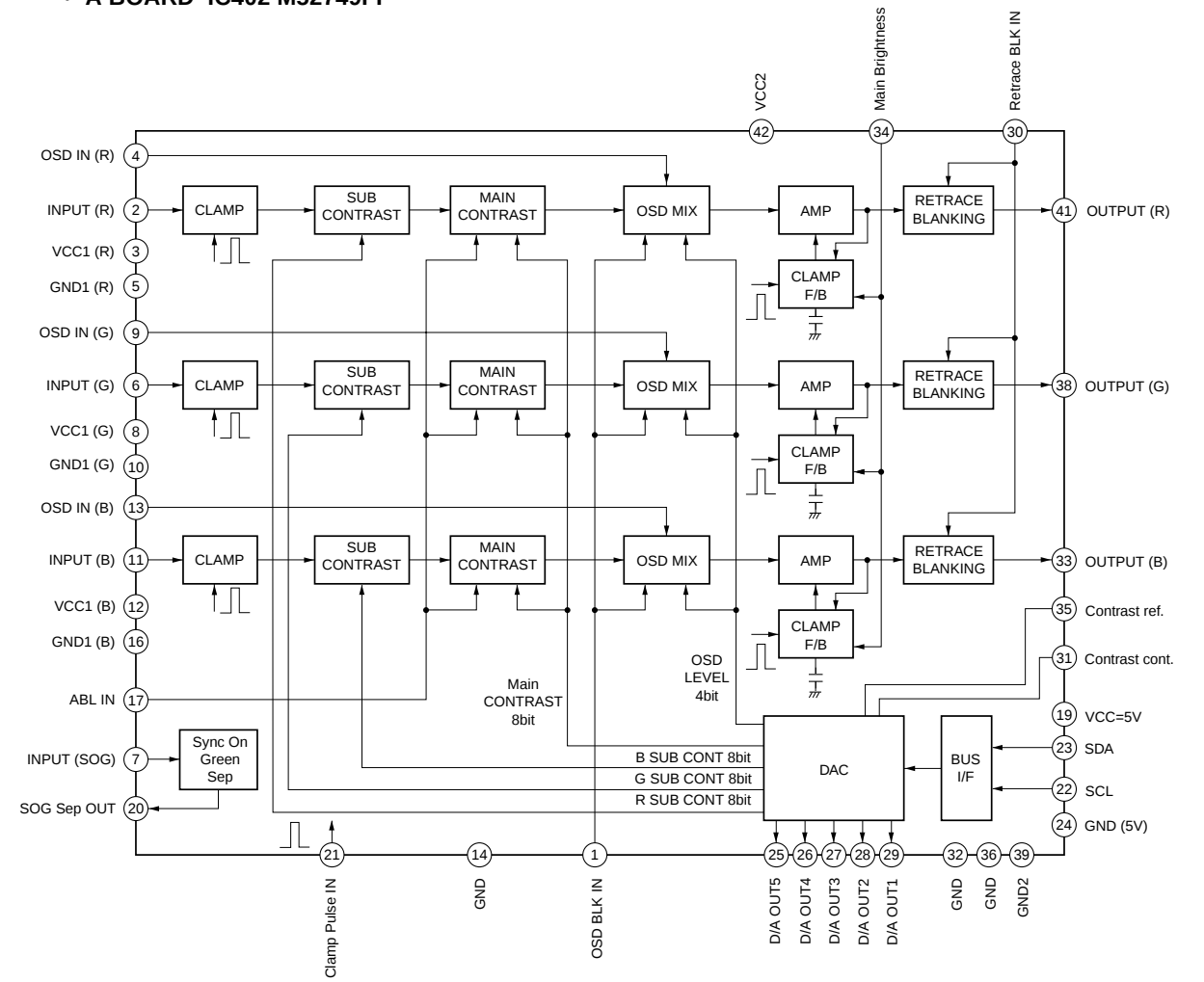




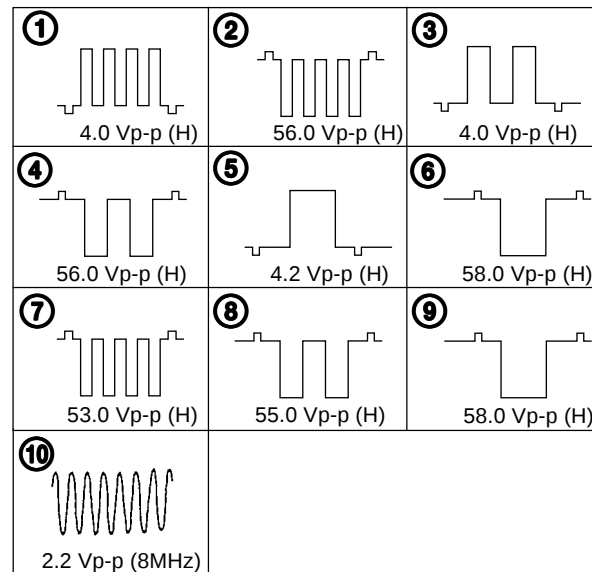
• A BOARD IC401 M52757FP



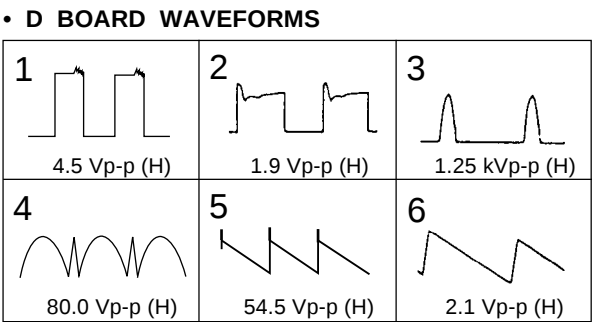
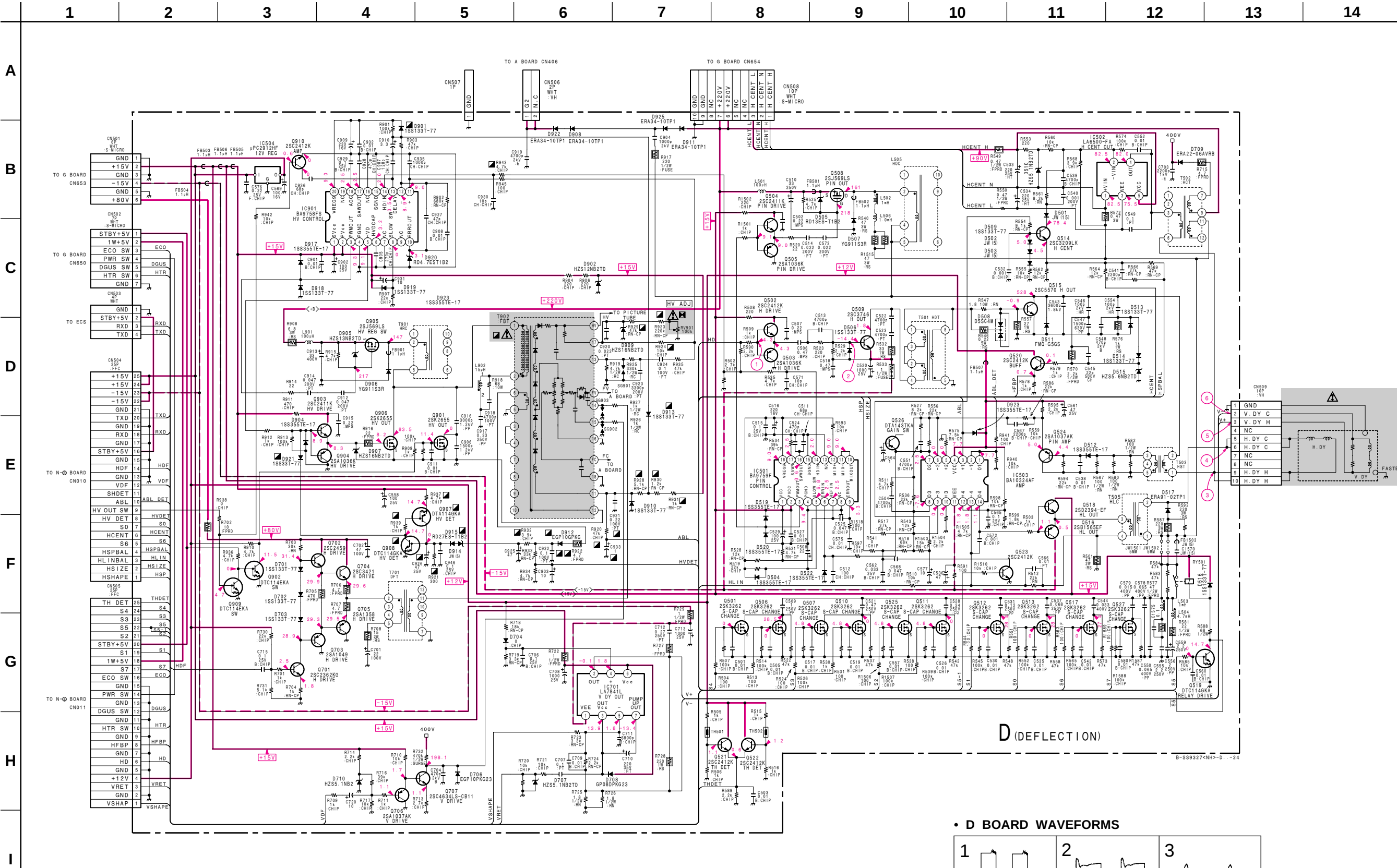
• A BOARD IC402 M52749FP



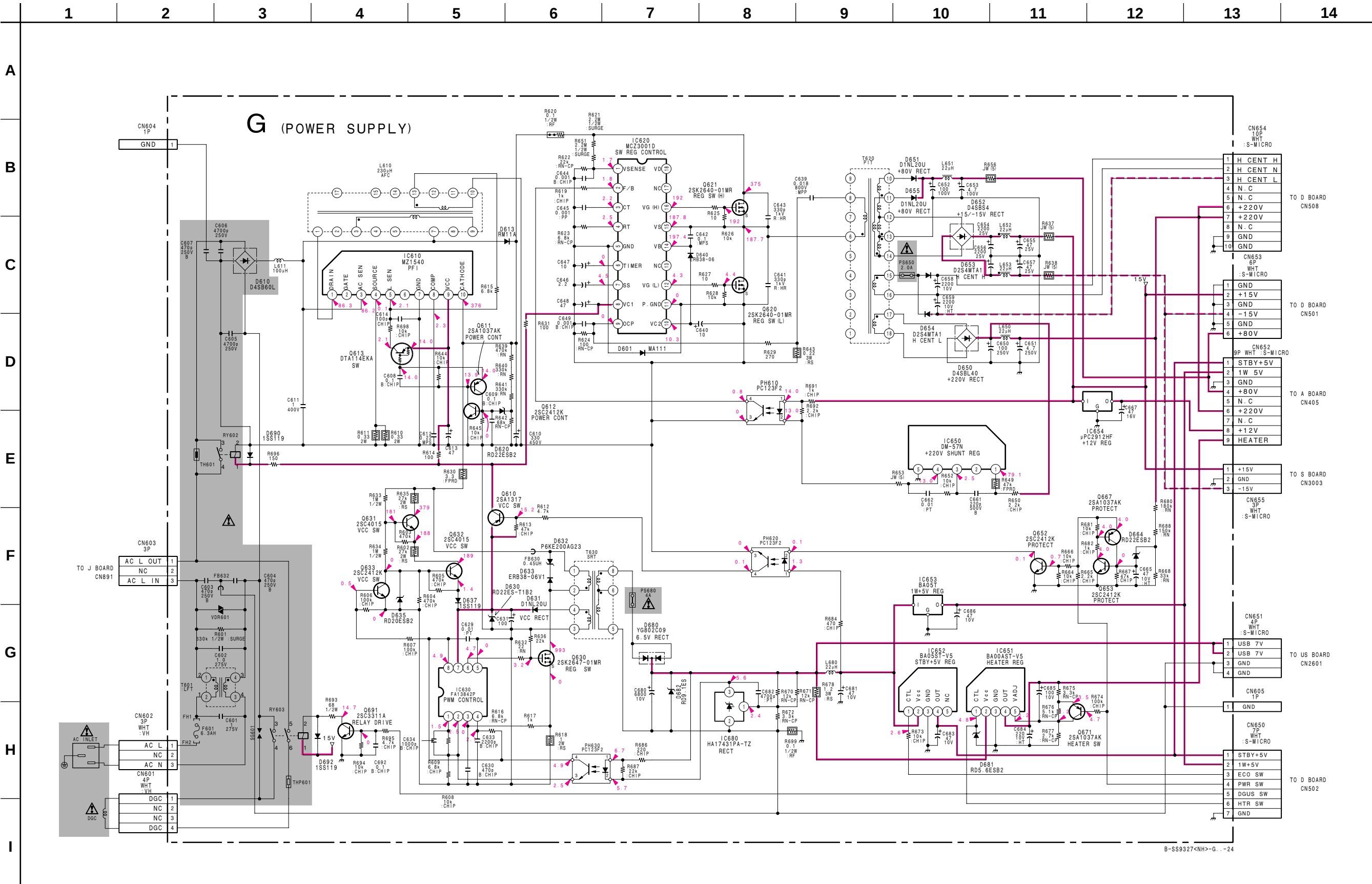
• A BOARD WAVEFORMS



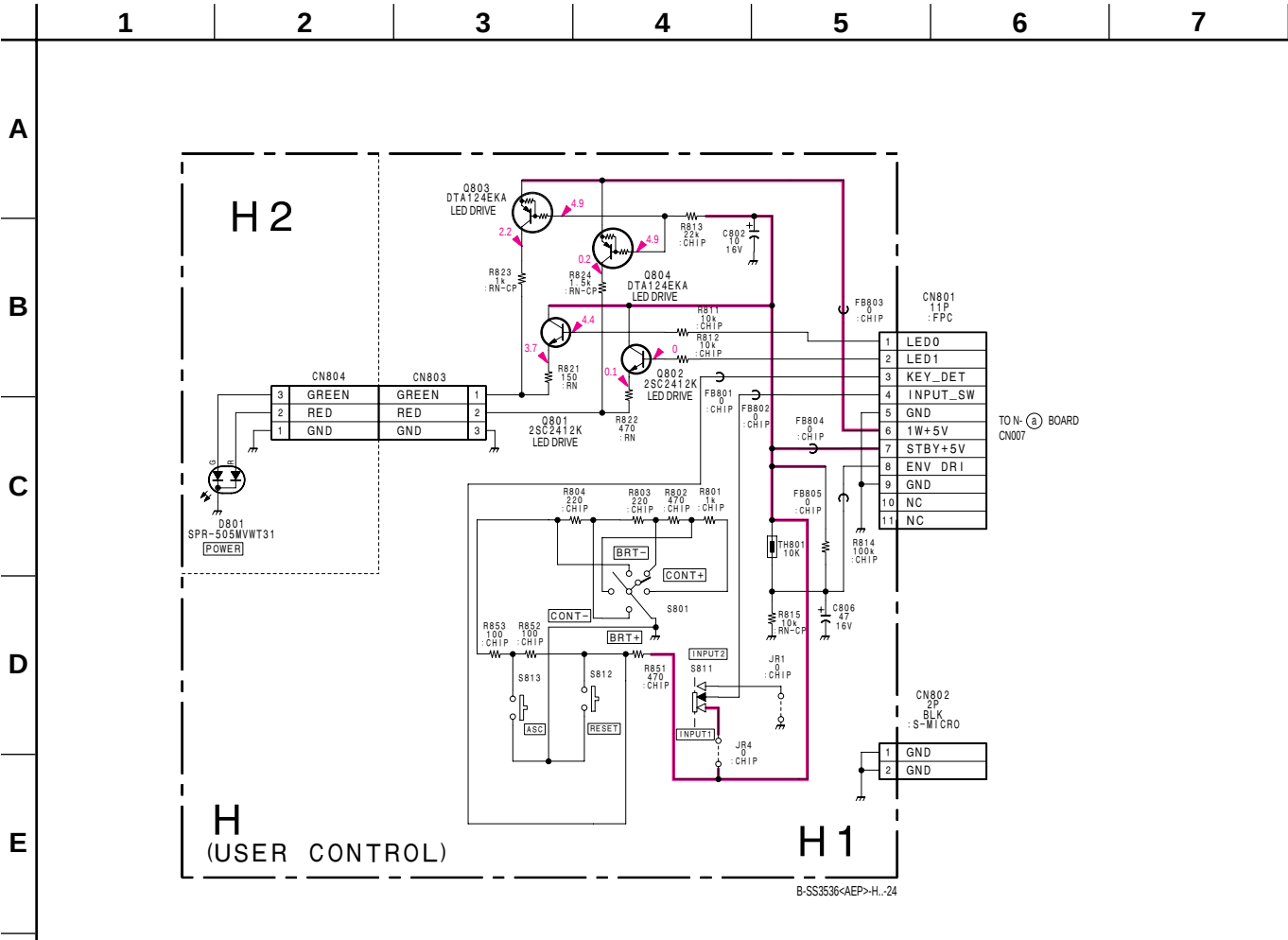
(2) Schematic Diagram of D Board



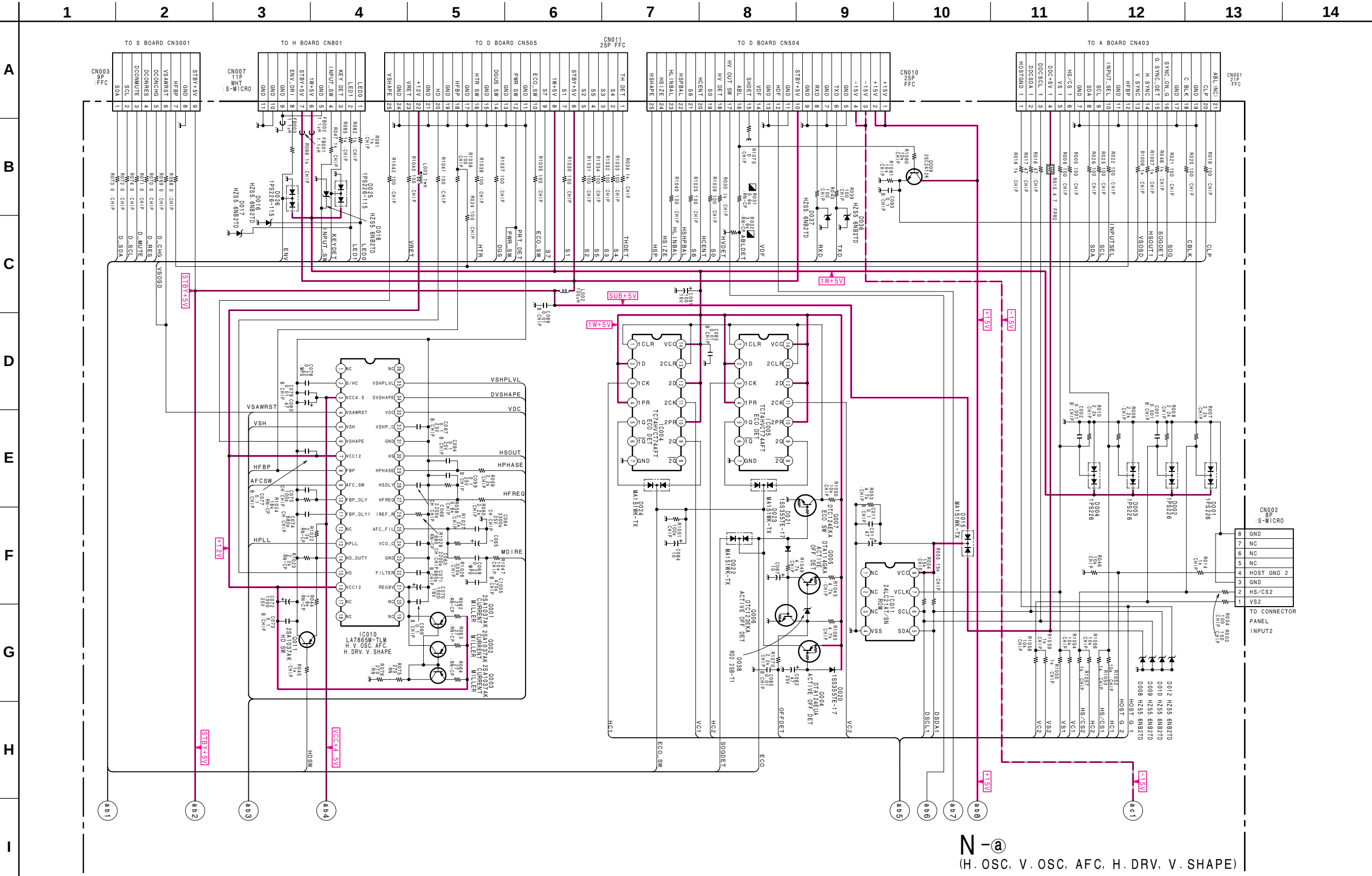
(3) Schematic Diagram of G Board



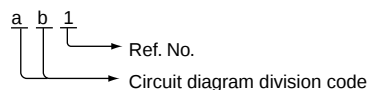
(4) Schematic Diagram of H Board

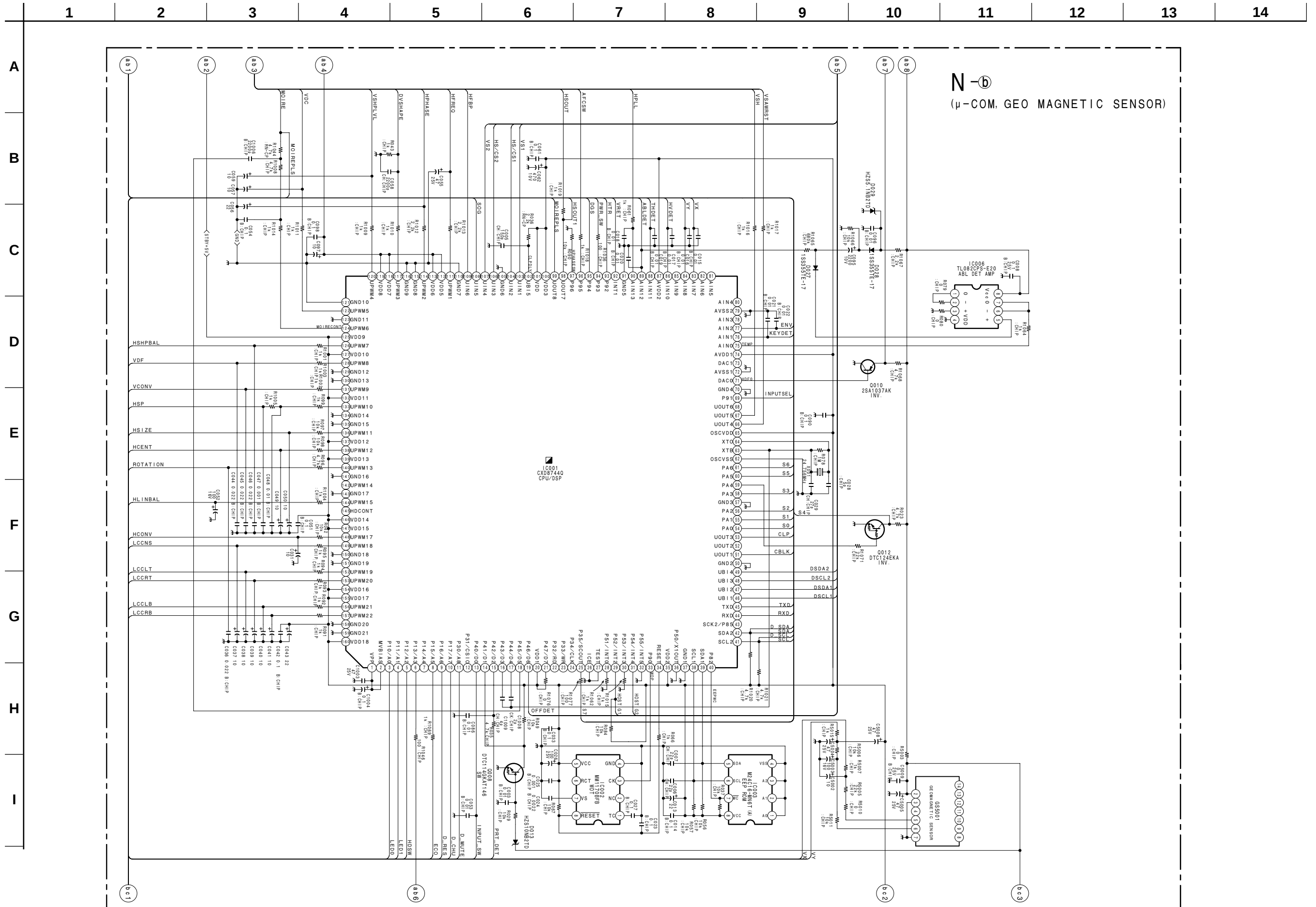


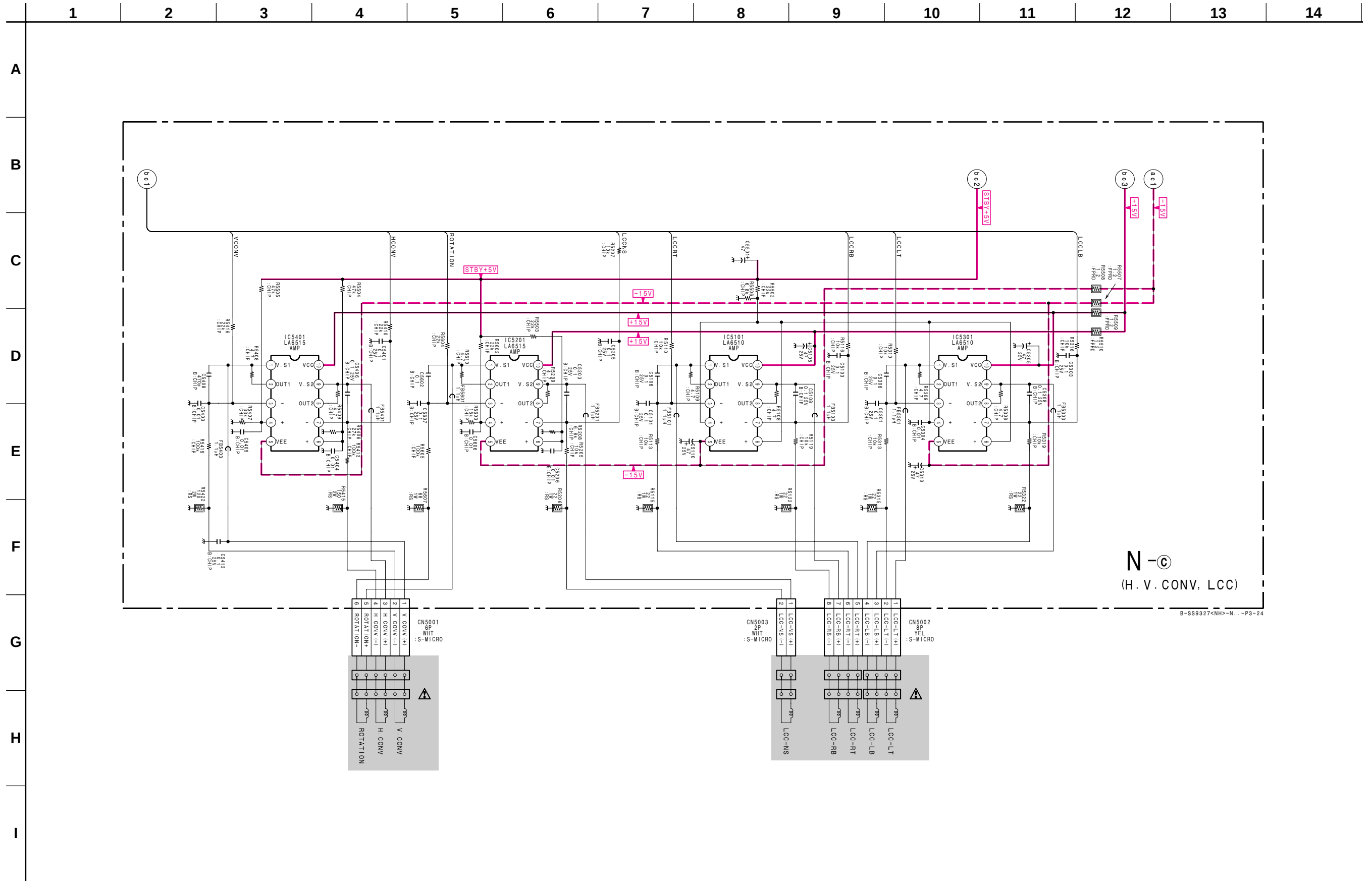
(6) Schematic Diagrams of N (a, b, c) Board



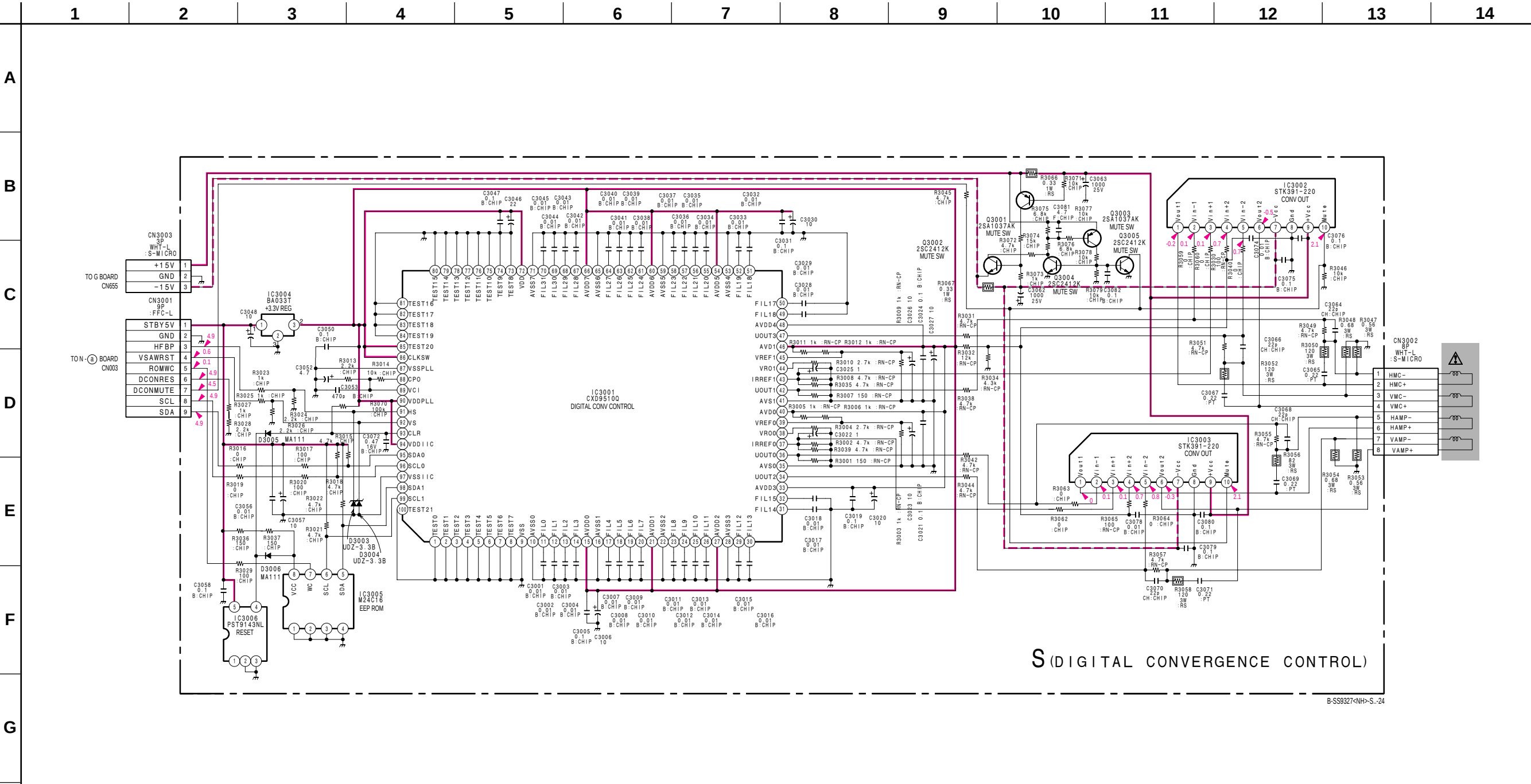
• Divided circuit diagram
One sheet of D board circuit diagram is divided into three sheets, each having the code D-Ⓐ to D-Ⓒ. For example, the destination (ab1) on the code D-Ⓐ sheet is connected to (ab1) on the D-Ⓑ sheet.







(7) Schematic Diagram of S Board



(8) Schematic Diagram of US Board

